

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chun-Wen Cheng</td> <td>09/02/2010</td> </tr> <tr> <td>Chung-Hsien Lin</td> <td>09/01/2010</td> </tr> <tr> <td>Chia-Hua Chu</td> <td>09/02/2010</td> </tr> </tbody> </table>		Name	Execution Date	Chun-Wen Cheng	09/02/2010	Chung-Hsien Lin	09/01/2010	Chia-Hua Chu	09/02/2010
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Chun-Wen Cheng	09/02/2010								
Chung-Hsien Lin	09/01/2010								
Chia-Hua Chu	09/02/2010								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13710389</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13710389				
Property Type	Number								
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CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	David M. O'Dell								
Total Attachments: 2 source=2333_Assignment#page1.tif source=2333_Assignment#page2.tif									

OP \$40.00 13710389

**ASSIGNMENT**

WHEREAS, we,

- |     |                 |    |   |
|-----|-----------------|----|---|
| (1) | Chun-Wen Cheng  | of | No. 15, Alley 11, Lane 100, Jiafeng 1 <sup>st</sup> Street<br>Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (2) | Chung-Hsien Lin | of | 6, Creation Rd. 2, Hsinchu Science Park<br>Hsinchu, Taiwan 300, R.O.C.  |
| (3) | Chia-Hua Chu    | of | No. 1, Lane 176, Aikou 6 <sup>th</sup> Street<br>Zhubei City, Hsinchu County 302, Taiwan, R.O.C.              |

have invented certain improvements in

**WAFER LEVEL PACKAGING**

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on                    and assigned application number                   ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is, to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Chun-Wen Cheng

Residence Address: No. 15, Alley 11, Lane 100, Jiafeng 1<sup>st</sup> Street  
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2010.9.2

Chun-Wen Cheng  
Inventor Signature

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Inventor Name: Chung-Hsien Lin

Residence Address: 6, Creation Rd. 2, Hsinchu Science Park  
Hsinchu, Taiwan 300, R.O.C.

Dated: 2010.9.1

Chung-Hsien Lin  
Inventor Signature

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Inventor Name: Chia-Hua Chu

Residence Address: No. 1, Lane 176, Aikou 6<sup>th</sup> Street  
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2010.9.2

Chia-hua Chu  
Inventor Signature